

UN-PACKAGED OR SEMI-PACKAGED ELECTRICALLY TESTED  
ELECTRONIC DEVICE FREE FROM INFANTILE MORTALITY AND  
PROCESS FOR MANUFACTURE THEREOF

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ABSTRACT

10 An un-packaged or semi-packaged, electrically tested electronic  
device, free from infantile mortality, characterized in that it comprises a  
silicon platelet or die (11) having a top surface and a bottom surface, in  
which an integrated circuit is realized externally accessible through a  
plurality of connection pads and an array of connection pins (10; 13; 14)  
which are mechanically and removably connected to said silicon die (11)  
by connection means and are electrically connected to the connection  
15 pads of said silicon die (11) by electric connection means (12).